

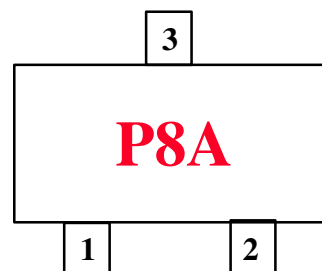
FLLD261

HIGH CONDUCTANCE LOW LEAKAGE DIODE

Pd ... 350 mW @ **T_A** = 25 Deg C

Bv ... 200 V (MIN) @ **I_R** = 5 uA

PACKAGE
TO-236AB (Low)



ABSOLUTE MAXIMUM RATINGS (NOTE 1)

TEMPERATURES

Storage Temperature -55 to +150 Degrees C
Operating Junction Temperature -55 to +150 Degrees C

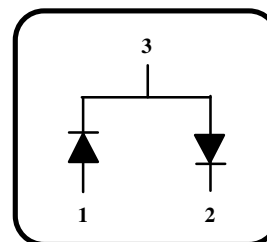
POWER DISSIPATION (NOTES 2 & 3)

Total Device Dissipation at **T_A** = 25 Deg C 350 mW
Derating Factor per Degree C 2.8 mW

VOLTAGES & CURRENTS

WIV Working Inverse Voltage 100 V
IO Average Rectified Current 250 mA
IF DC Forward Current 600 mA
if Recurrent Peak Forward Current 700 mA
if (surge) Peak Forward Surge Current
Pulse width = 1 second 1.0 A
Pulse width = 1 microsec 3.0 A

CONNECTION DIAGRAMS

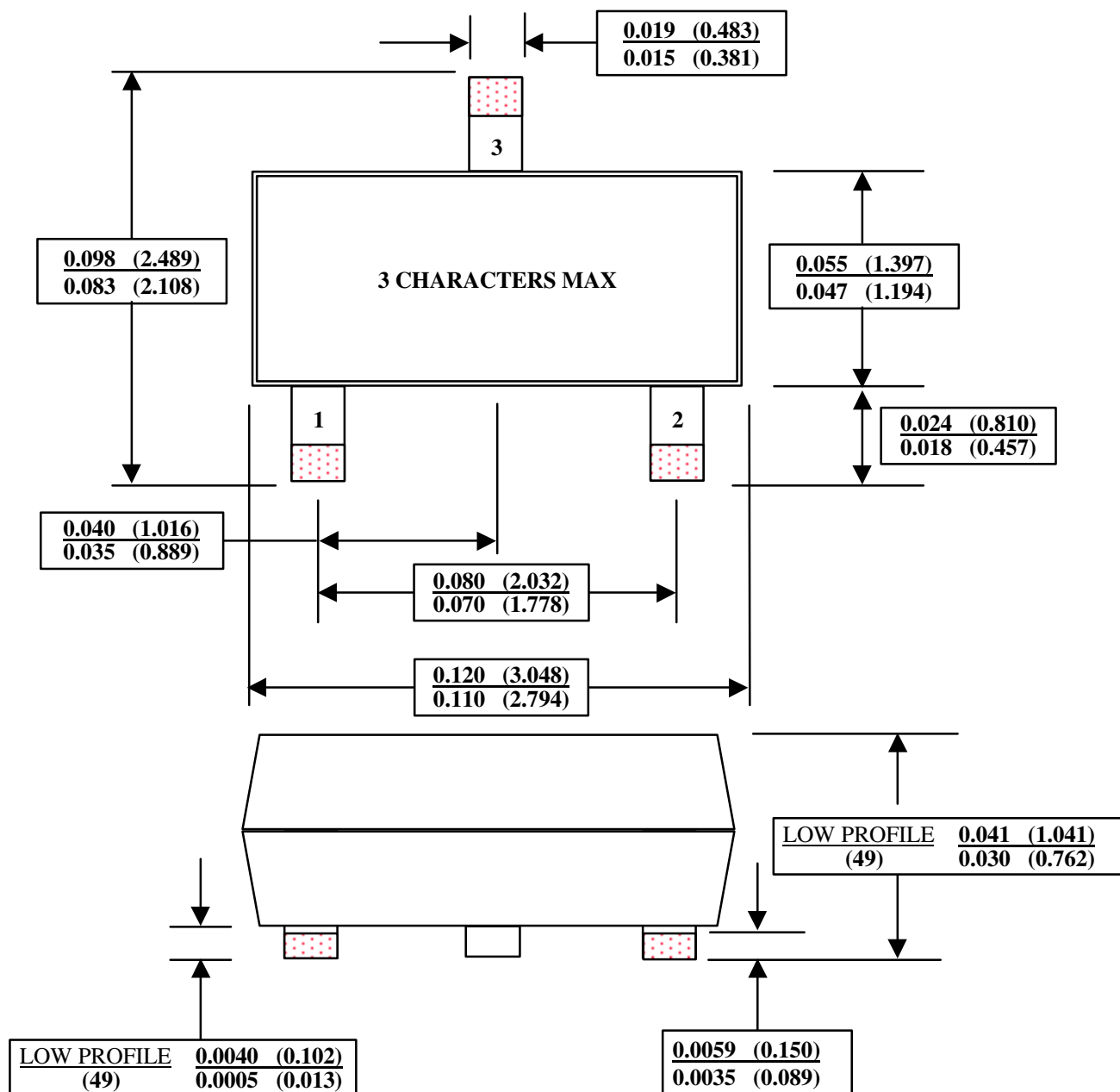


ELECTRICAL CHARACTERISTICS (25 Degrees C Ambient Temperature unless otherwise stated)

| SYM | CHARACTERISTICS | MIN | MAX | UNITS | TEST CONDITIONS |
|-----------------|---------------------------------|-----|------------|----------|--|
| Bv | Breakdown Voltage | 200 | | V | I _R = 5.0 uA |
| I _R | Reverse Voltage Leakage Current | | 5.0 5.0 | nA uA | V _R = 100 V V _R = 100 V T _A = 150 Deg C |
| V _F | Forward Voltage | | 1.40 | V | I _F = 200 mA |
| C _T | Diode Capacitance | | 4.0 | pF | V _R = 1.0 V f = 1.0 MHz |
| TRR | Reverse Recovery Time | | 400 | ns | I _F = I _R = 50 to 400 mA I _{RR} = 10% I _R R _L = 100 ohms |
| T _{FR} | Forward Recovery Time | | 10 | ns | I _F = 10 mA |
| V _{FM} | Peak Forward Voltage | | 0.9 Typ | V | I _F = 10 mA Rise Time = 5 ns +/-20% |

NOTES:

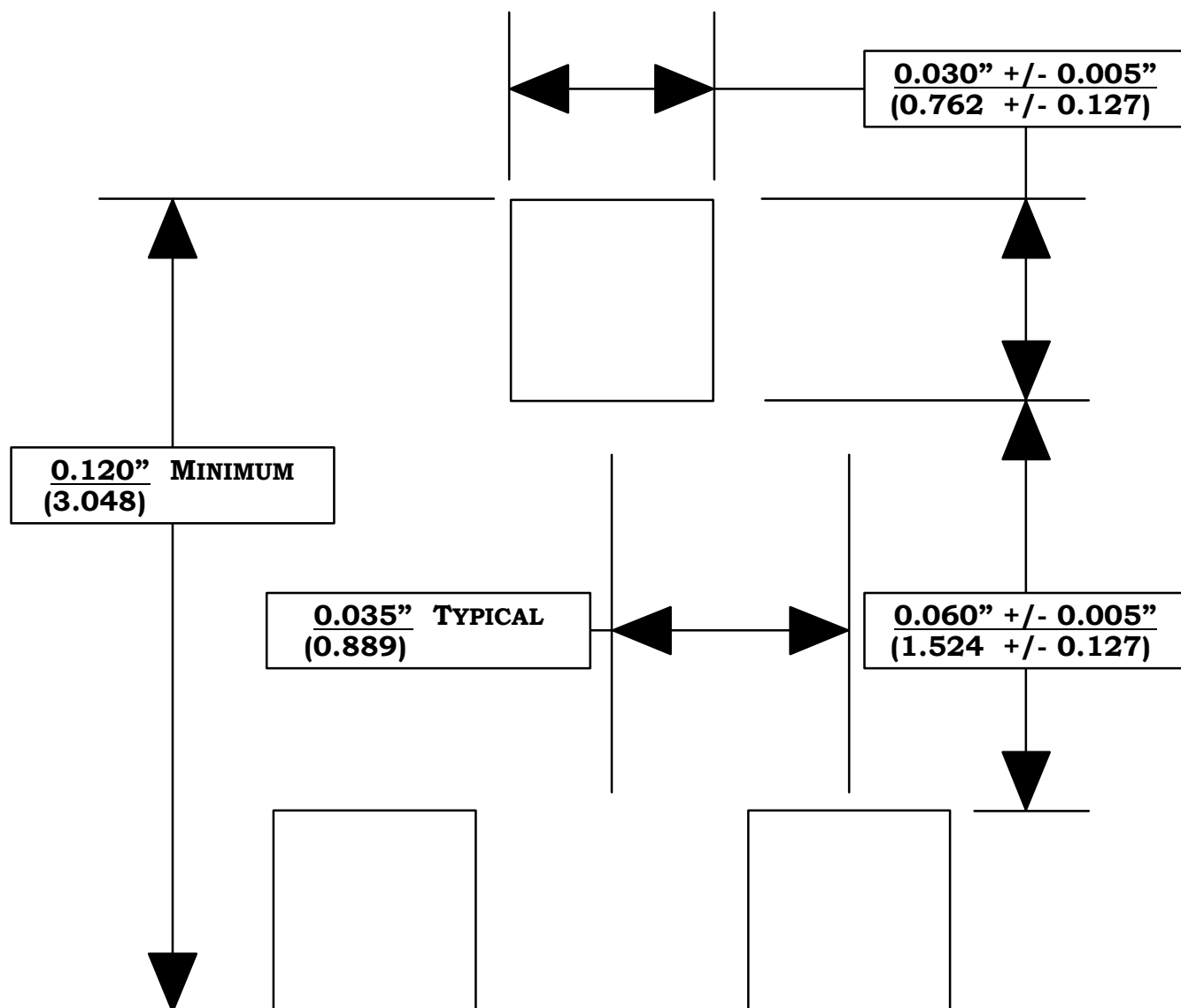
- These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.
- These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.



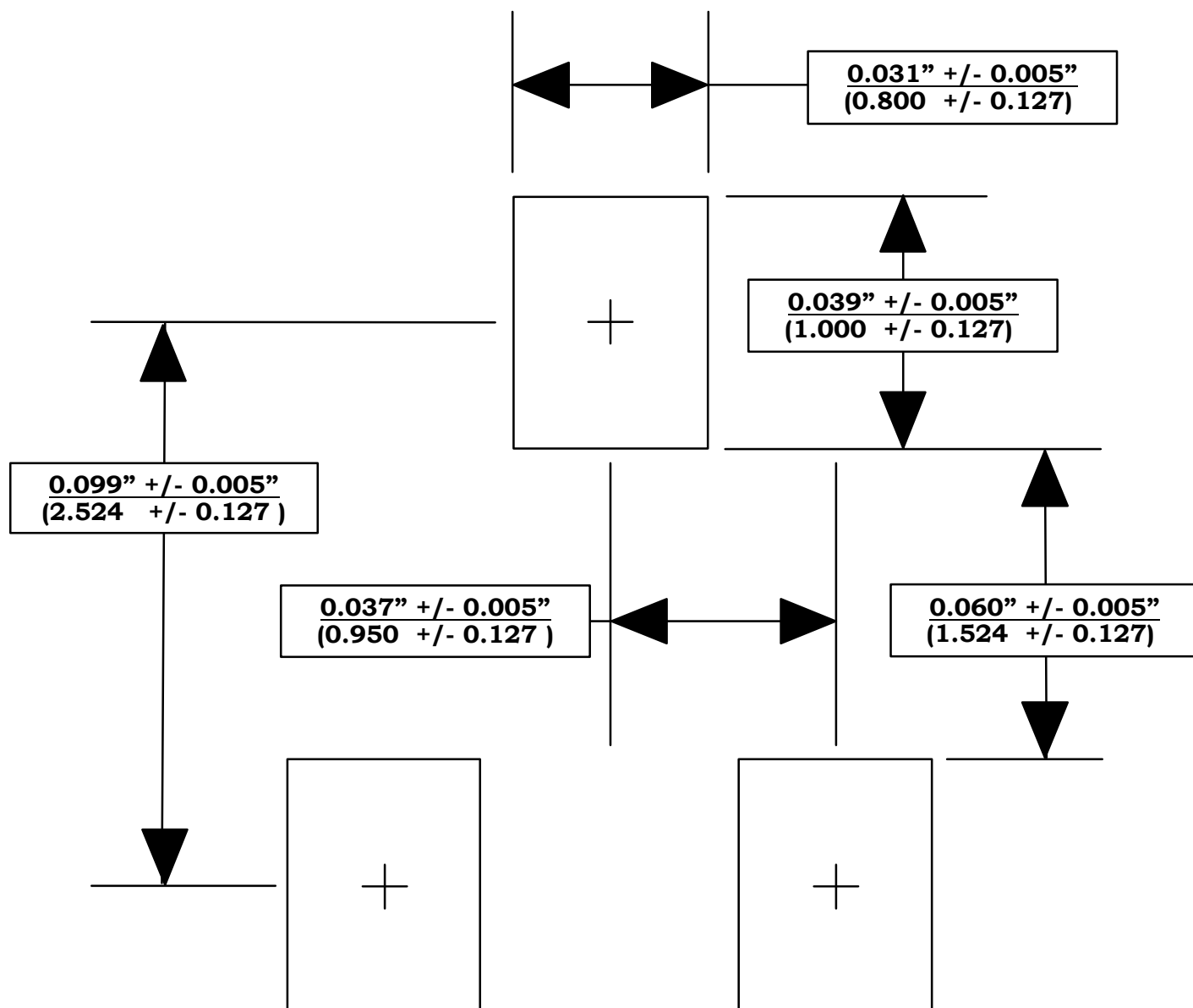
SOT-23 (DIODE)

TO-236AB (LOW PROFILE)

11-March-1997



**RECOMMENDED SOLDER PADS
FOR
SOT-23**



**RECOMMENDED SOLDER PADS
FOR
U.S., European & Japanese (SC-59)
SOT-23**

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|--------------------------|------------------------|---|
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